

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT5711769

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
KENZO DATE	08/26/2019
RECEIVING PARTY DATA	
Name:	ADABIT JAPAN LLC
Street Address:	3-35-16 OTSUKA, BUNKYO-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	112-0012
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	35506033
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	9494701672
Email:	muramatsulaw@outlook.com
Correspondent Name:	YASUO MURAMATSU
Address Line 1:	62 TESSERA AVENUE
Address Line 4:	FOOTHILL RANCH, CALIFORNIA 92610
ATTORNEY DOCKET NUMBER:	DATEK.001DUS
NAME OF SUBMITTER:	YASUO MURAMATSU
SIGNATURE:	/Yasuo Muramatsu/
DATE SIGNED:	09/10/2019
Total Attachments: 1	
source=ASN-DATEK-D1-signed#page1.tif	

ASSIGNMENT

WHEREAS, I, **Kenzo Date**, a resident of 3-35-16 Otsuka, Bunkyo-ku, Tokyo, 112-0012 Japan, have invented certain new and useful improvements in "**STAND FOR A MOBILE TELEPHONE**", an application of which for letters of design patent for the United States has been filed with the application No. 35/506,033;

AND WHEREAS, **ADABIT JAPAN LLC** (hereinafter "**ASSIGNEE**"), a Japanese corporation, with its principal place of business at 3-35-16 Otsuka, Bunkyo-ku, Tokyo, 112-0012 Japan, desires to acquire the entire right, title, and interest in and to the said improvements and the said application:

NOW, THEREFORE, in the receipt of valuable consideration which is hereby acknowledged, I do hereby acknowledge that I have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said **ASSIGNEE**, its successors, legal representatives and assigns, the entire right, title, and interest throughout the world in, to and under the said improvements, and the said application and all divisions, renewals and continuations thereof, and all letters patent of the United States which may be granted thereon and all reissues and extensions thereof, and all rights of priority under International Conventions and applications for Letters Patent which may hereafter be filed for said improvements in any country or countries foreign to the United States, and all Letters Patent which may be granted for said improvements in any country or countries foreign to the United States and all extensions, renewals and reissues thereof; and I hereby authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said improvements to the said **ASSIGNEE**, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND I HEREBY covenant and agree that I will communicate to the said **ASSIGNEE**, its successors, legal representatives and assigns, any facts known to us respecting said improvements, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid the said **ASSIGNEE**, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said improvements in all countries.

This 26th day of August 2019



Kenzo Date